

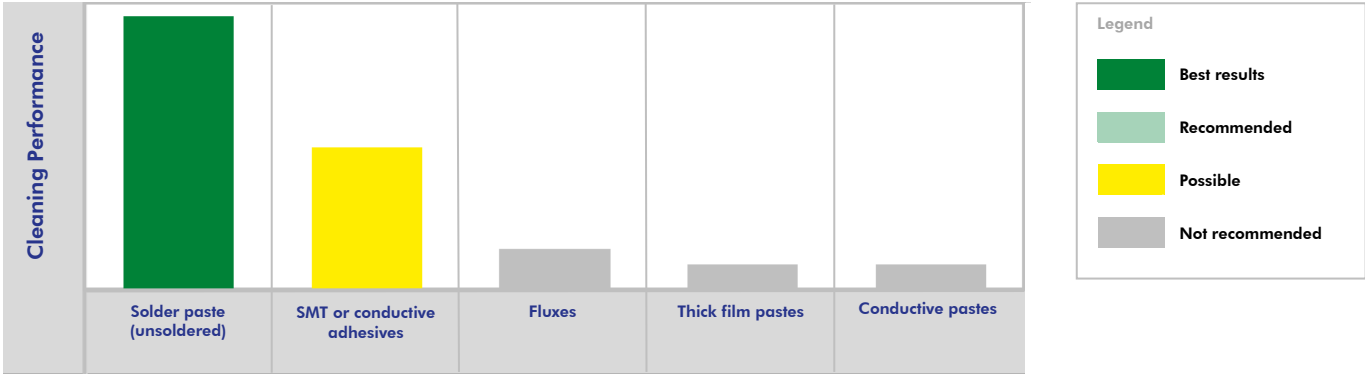
ZESTRON® SW

Cleaning agent for stencil underside wiping in SMT printers



ZESTRON® SW is a solvent-based cleaner with a high flash point, which was developed together with leading SMT printer manufacturers and specifically designed for the use in SMT printers without vacuum drying. ZESTRON® SW achieves reproducible cleaning results and dries residue- free, thus it increases the reliability of the printing process.

Areas of application – Stencil underside wiping in SMT printers



Advantages compared to other cleaners

- Due to its wide process window ZESTRON® SW reliably removes solder pastes from the stencil underside.
- Dries fast and residue-free on stencils after dry wipe.
- Good delineation stability and reduced solder balling.
- Reduces the amount of cleaning cycles.
- Unlike Isopropanol (flash point: 12°C/54°F) ZESTRON® SW (flash point: 67°C/153°F) dramatically increases operational safety while operating stencil printing equipment.
- ZESTRON® SW is biodegradable.
- The product has been approved by leading international manufacturers for the use in their stencil printers. Written approvals can be obtained from ZESTRON.

Process Steps

Cleaning Process	1. Cleaning	2. Drying
SMT printer with or without vacuum drying	ZESTRON® SW	Dry fleece or vacuum

## Independent Test Center - Largest choice of leading machines, chemistry & analytics



Machine Test Center



Analytical Center

Visit our Machine Test Center and clean your stencils & screens under production conditions in cleaning machines of leading international equipment suppliers. Our process engineers will help you independently of any supplier to find the most suitable combination of equipment & cleaning agent for your requirements. Following the cleaning trials, all results will be reviewed immediately in our Analytical Center to verify the required cleanliness.




**Contact ZESTRON's process engineers for cleaning trials:**

Europe: +49 8453 41995 318; [techsupport@zestron.com](mailto:techsupport@zestron.com) / South Asia: +604 (3996) 100; [support@zestronasia.com](mailto:support@zestronasia.com)

## Technical Data

Density	(g/ccm) at 20°C/68°F	0.89
Surface tension	(mN/m) at 25°C/77°F	27.6
Boiling range	°C/°F	100 – 171 / 212 – 340
Flash point	°C/°F	67 / 153
pH value	10g/l H <sub>2</sub> O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 3
Cleaning temperature	°C/°F	Room temperature
Application concentration	Ready-to-use	Pure
HMIS Rating	Health-Flammability-Reactivity	1 – 2 – 0

## Product Features & Cleaning Standards

	100% compliance with EU guidelines (RoHS 1, 2 & 3, WEEE)	<p>After cleaning the underside of SMT stencils used for production with ZESTRON® SW, PCBs meet the requirements of the following standard:</p> <ul style="list-style-type: none"> <li>IPC-9202 Material and Process Characterization/Qualification</li> </ul>
	Extensively tested and suitable for cleaning lead-free solder pastes	
	Product is free of any critical substances according to SIN & SVHC lists	

## Environmental, health & safety regulations

- ZESTRON® SW is formulated free of any halogenated compounds and biodegradable.
- According to EU standards, special labelling is necessary, but the product is not a hazardous material.
- Refer to the SDS for specific handling precautions and instructions.

## Availability & Storage

1 Liter	✓
5 Liter	✓
25 Liter	✓
200 Liter	✓

- Available as ready-to-use solution
- Store ZESTRON® SW in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.



## Further product information

- **Material Compatibility**  
Please review the Material Compatibility overview before using the cleaning agent
- **Evaluation guideline**  
Guideline for stencil underside wiping in SMT printers
- **Process reliability**  
Additional information about underside wiping in printers
- **Safety data sheet**